

NOTES :

- MATERIAL :
 - HOUSING:LCP UL94 V-0, BLACK COLOR.
 - SHELL: STAINLESS STEEL
 - CONTACT: COPPER ALLOY
- FINISH :
 - CONTACT: GOLD PLATING ON CONTACT AREA, GOLD FLASH ON SOLDERTAIL AREA. 50 μ MIN NICKEL PLATING OVERALL.
 - SHELL: 30 μ MIN SOLDERABLE NICKEL PLATING OVERALL. GOLD FLASH ON SOLDERTAIL AREA.

3. ELECTRICAL CHARACTERISTICS:

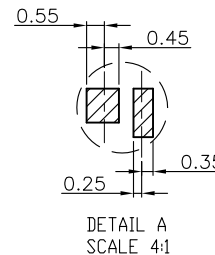
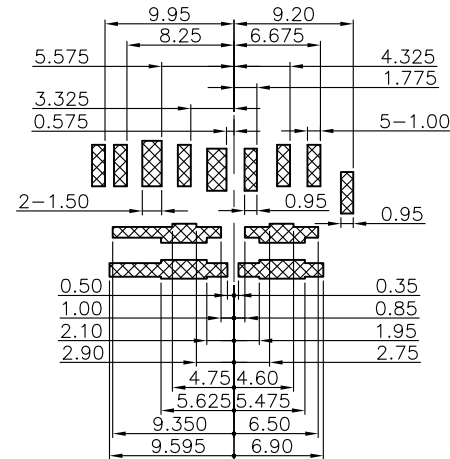
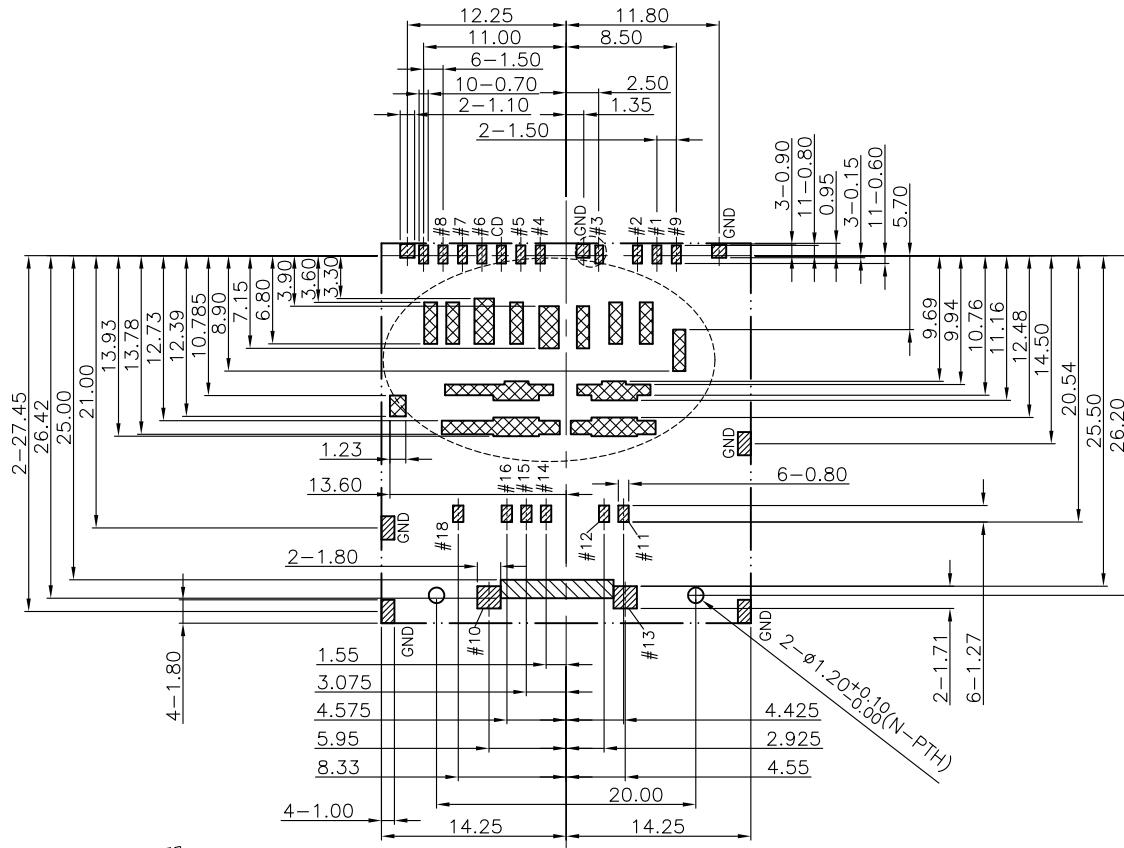
- OPERATING VOLTAGE : 100V AC(rms)/DC.
- CURRENT RATING : 0.5 A.
- OPERATING TEMPERATURE: -25°C~+85°C.
- CONTACT RESISTANCE: 100 m OHMS MAX.
- INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
- DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

PART.NO.: TW243-AP401-**

- 08: 功能区镀金1U*, 锡脚Gold Flash
- 09: 功能区镀金3U*, 锡脚Gold Flash
- 10: 功能区镀金5U*, 锡脚Gold Flash
- 11: 功能区镀金15U*, 锡脚Gold Flash
- 12: 功能区镀金30U*, 锡脚Gold Flash

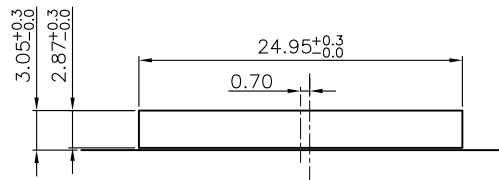
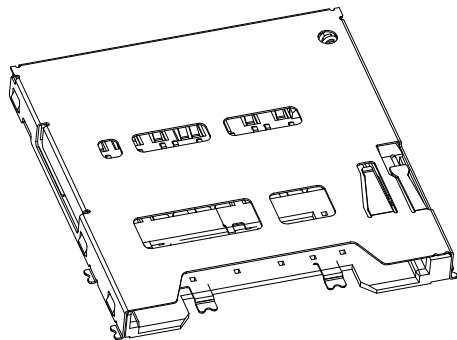
GENERAL TOLERANCE	DWG.NO.	TW243-AP401-00	PART.NO.	TW243-AP401-**	DRAWN	Toff 2021.10.13
x. \pm 0.50	REV.	A	TITLE	SD7.0 Push H2.90 conn.	CHECKED	
.x \pm 0.25	SIZE		SHEET	1 OF 3	APPROVED	
.xx \pm 0.15	A4					

UNIT	mm	SCALE	1:1
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RECOMMENDED PCB LAYOUT(TOP VIEW)
TOLERANCE:±0.05mm

- PAD AREA
- KEEP OUT AREA
- NO COPPER AREA (NO TRACE & VIA & GND)
- GND PATTERN ONLY



RECOMMENDED ID DIMENSION

OPEN/CLOSE OF SD SWITCH:

CD INSETION CARD: ON
GND NORMAL: OFF

WP WRITE ENABLE: ON
GND WRITE PROTECTED: OFF
NORMAL: OFF

PIN #	ASSIGNMENT	SD Mode	UHS II Mode	PCIe Mode
		Name		
#9	DAT2	DAT2		CLKREQ#
#1	DATA3	DATA3		PERST#
#2	CMD	CMD		-
#3	VSS1	VSS1		VSS1
#4	VDD	VDD		VDD1
#5	CLK	CLK		-
#6	VSS2	VSS2		VSS2
CD	CARD DETECT			
#7	DAT0	DAT0		REFCLK+
#8	DAT1	DAT1		REFCLK-
WP	WRITE PROTECT			
#10		VSS3		VSS3
#11	D0+			PCIe_Tx+
#12	D0-			PCIe_Tx-
#13	VSS4			VSS4
#14	VDD2			VDD2
#15	D1-			PCIe_Rx-
#16	D1+			PCIe_Rx+
#17	VSS5			VSS5
#18				VDD3

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x.±0.50	REV.	A	TITLE	SD7.0 Push H2.90 conn.	CHECKED	
.x±0.25	SIZE	A4	SHEET	2 OF 3	APPROVED	
.xx±0.15	A4					

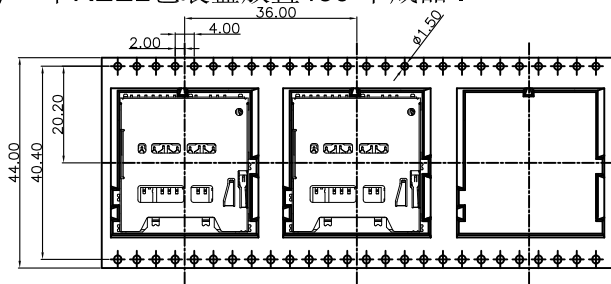
UNIT mm SCALE 1:1

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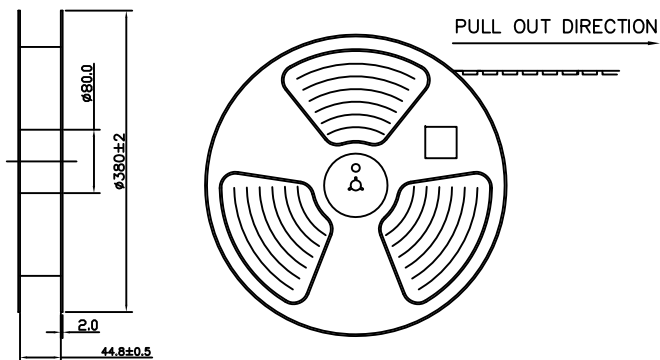
包装作业规范

包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

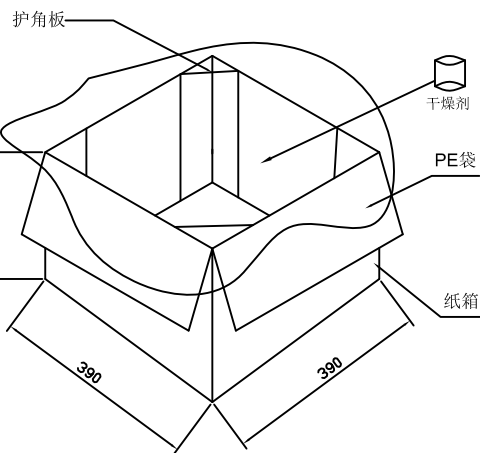
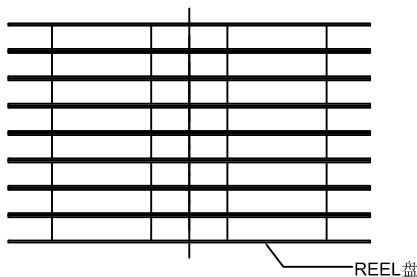
- 一.
- 1) 将成品一一放入REEL包装盘内,依同一方向放入.
 - 2) 包装时,如图所示.
 - 3) 一个REEL包装盘放置450个成品.



- 二.
- 1) 装盘前先把前面空20pcs产品,然后再开始装盘,尾端也需空20pcs产品,上带加长200mm.
 - 2) 装满成品的REEL包装盘如下图所示.



- 三.
- 1) 每箱装6盘REEL包装盘.
 - 2) 每箱放置2700PCS的成品.



- 四.
- 1) 用TAPE将纸箱封实.

备注 (REMARK)

1. 若有未装满之零数箱,必须以缓冲材塞满.

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.x±0.25	SIZE		SHEET	3 OF 3	APPROVED	
.xx±0.15	A4					

UNIT	mm	SCALE	1:1
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